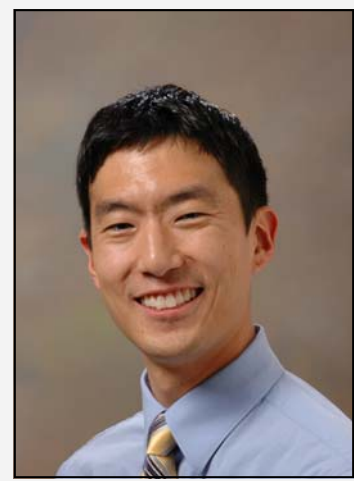


Single-Event Characterization of the 28 nm Xilinx Kintex-7 Field-Programmable Gate Array under Heavy-Ion Irradiation



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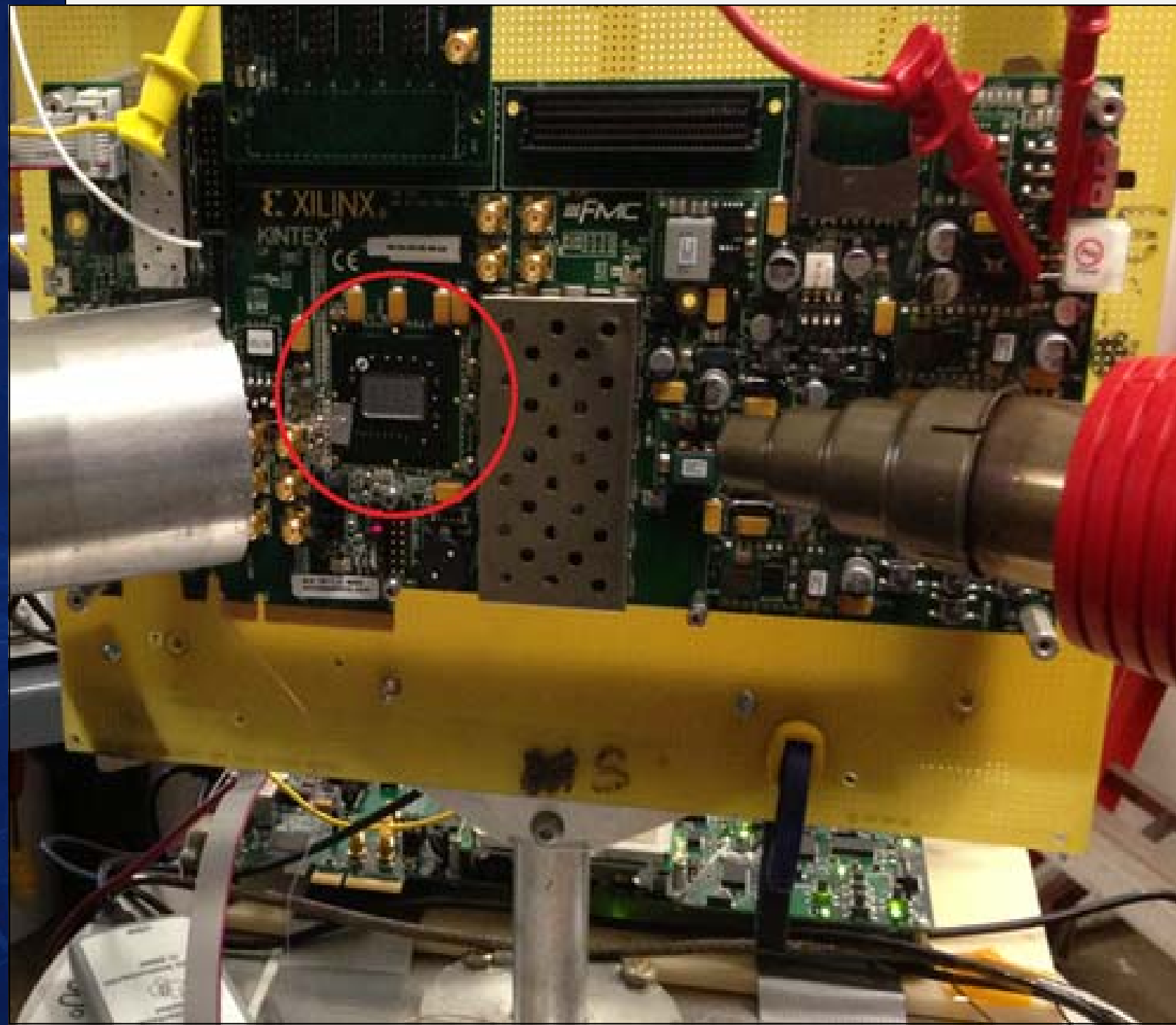
Abstract

This study examines the single-event response of the Xilinx 28 nm Kintex-7 FPGA irradiated with heavy ions. Results for single-event effects on configuration SRAM cells, user-accessible Flip-Flop cells, and BlockRAM™ memory are provided. This study also describes an unconventional single-event latch-up signature observed during testing.

Introduction

This study examines the single-event effects susceptibility of the Xilinx Kintex-7 Field-Programmable Gate Array. The Kintex-7 is the mid-range offering in the Xilinx Series-7 family of cutting edge FPGAs built on TSMC's 28 nm, high-κ metal gate process technology [1]. The purpose of this work is to determine the flight-worthiness and feasibility of utilizing these parts in space environments.

Device	Xilinx Kintex-7 XC7K325T
Package	FBG900C (flip-chip lidless, commercial)
Configuration	91,530,240 bits
Flip-Flops	407,600
BlockRAM™	16,404,480 bits
Slice Logic	50,950 (4 LUTs and 8 FFs per slice)
Other untested device features	10 clock management tiles, 1 PCI Express block, 16 Multi-Gigabit Transceiver blocks, 12-bit ADC, 840 DSP slices



Test setup at Texas A&M Cyclotron. Illustrated is the Kintex-7 DUT (circled), beam output (left), and heat-gun utilized during SEL testing (right).

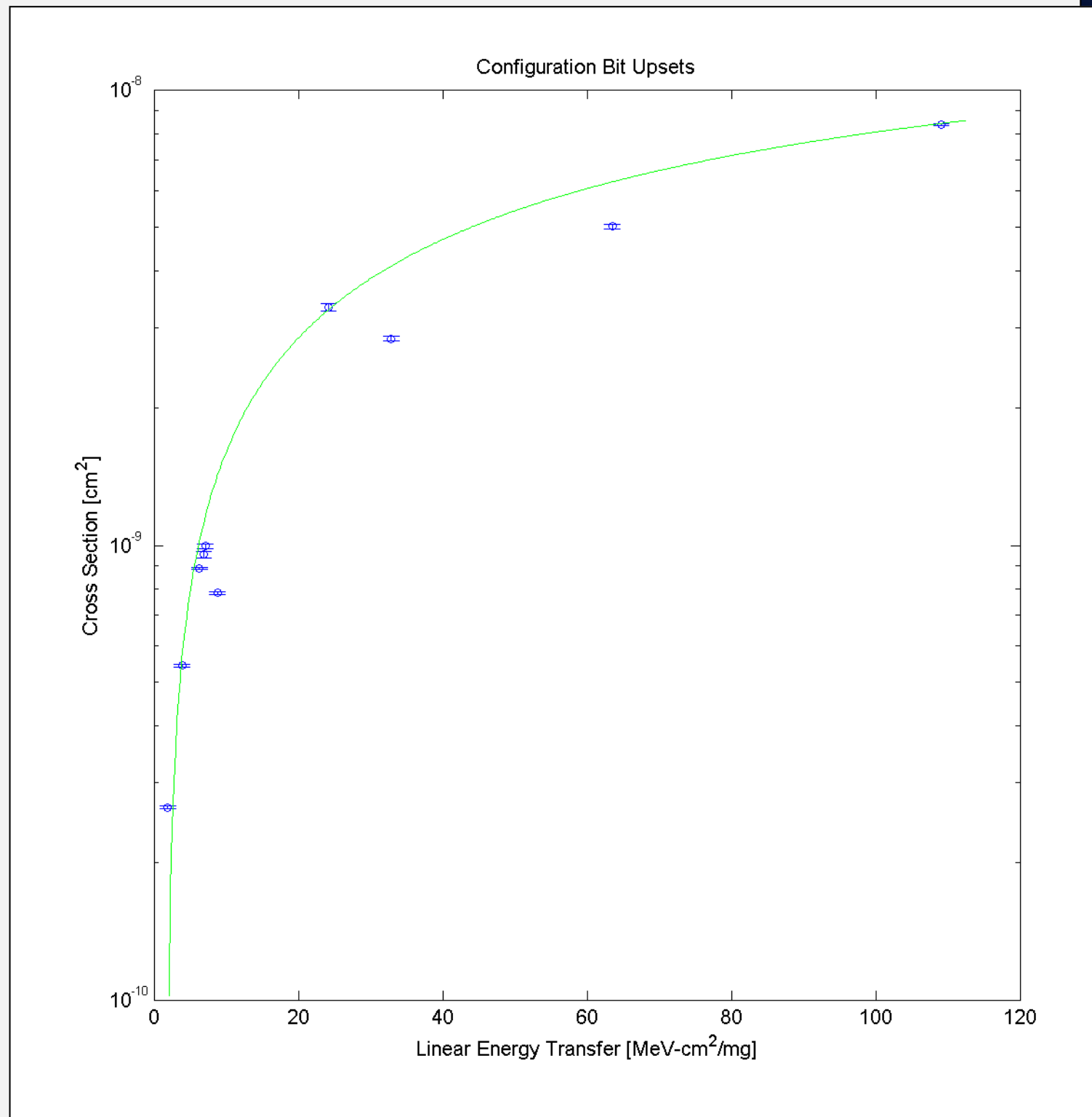
SEU Results

I. Configuration Memory Bits

- Static configuration memory test performed by configuring, irradiating, and then reading back the device.
- Comparisons are masked to only include bits pertinent to device operation and to exclude dynamic content (such as user flip-flop data).
- Multiple-bit SEU clusters in configuration words and adjacent logical addresses seem to indicate some physical interleaving of bits. An analysis of these multiple-bit events and their implication to inferring physical device layout is discussed in [3].



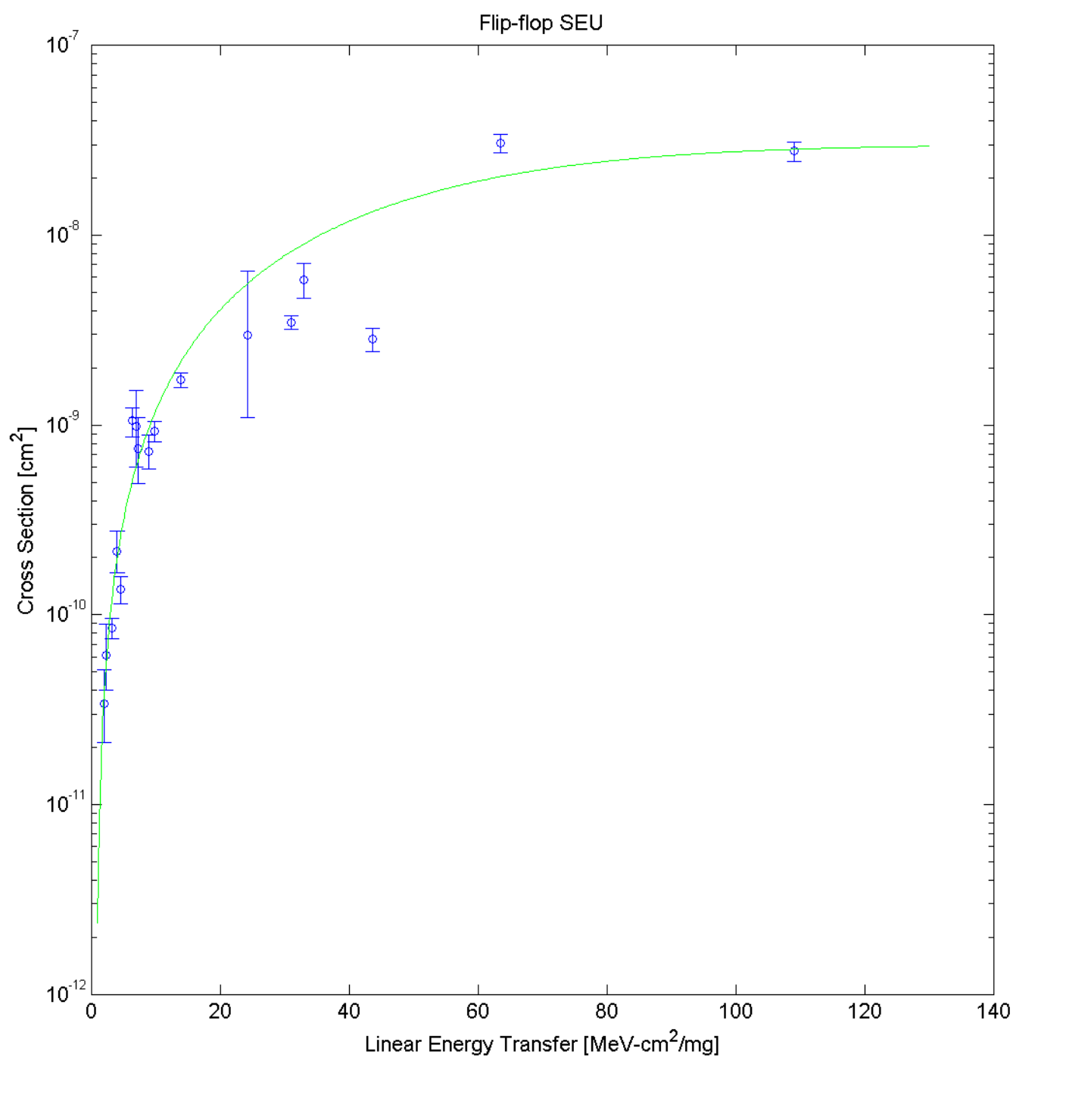
A pictorial representation of multiple-bit upset shapes. Configuration words are ordered into columns. Horizontally adjacent bits are in logically adjacent words.



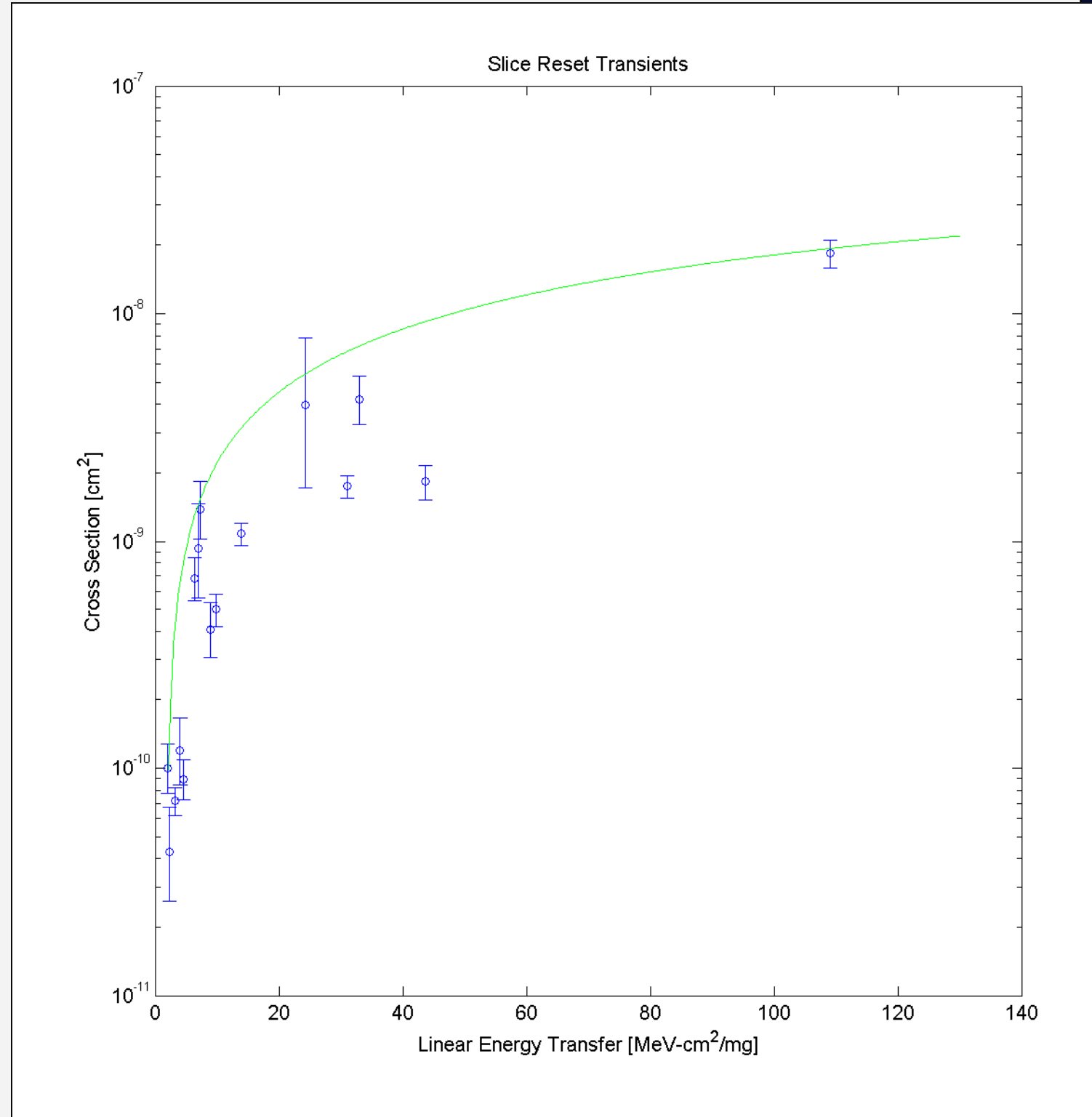
Weibull curve illustrating the per-bit cross-section for the configuration memory bits.

II. Flip-Flops

- Flip-flops tested through a test design containing several long flip-flop chains. Half of the chains were initialized to 1 and half were initialized to 0. Flip-flops were not clocked during irradiation.
- Resets were configured to either reset or preset the flip-flop to ensure that reset transients would always flip the value of the flip-flop opposite of its initialized value.
- Results indicated two error signatures: (1) a flip of a single flip-flop data value due to SEU or possibly by reset transient only affecting a single flip-flop; and (2) SET-induced reset that would travel down a physical FPGA column affecting anywhere from 1 to 42 slices (most often 1 or 2).
- Single value flips from SEU or single-cell resets were not biased to either 0- or 1-initialized flip-flops.
- Observed slice reset transients are especially important to note for designers, as this phenomenon could be particularly defeating to design mitigation strategies (most notably TMR).



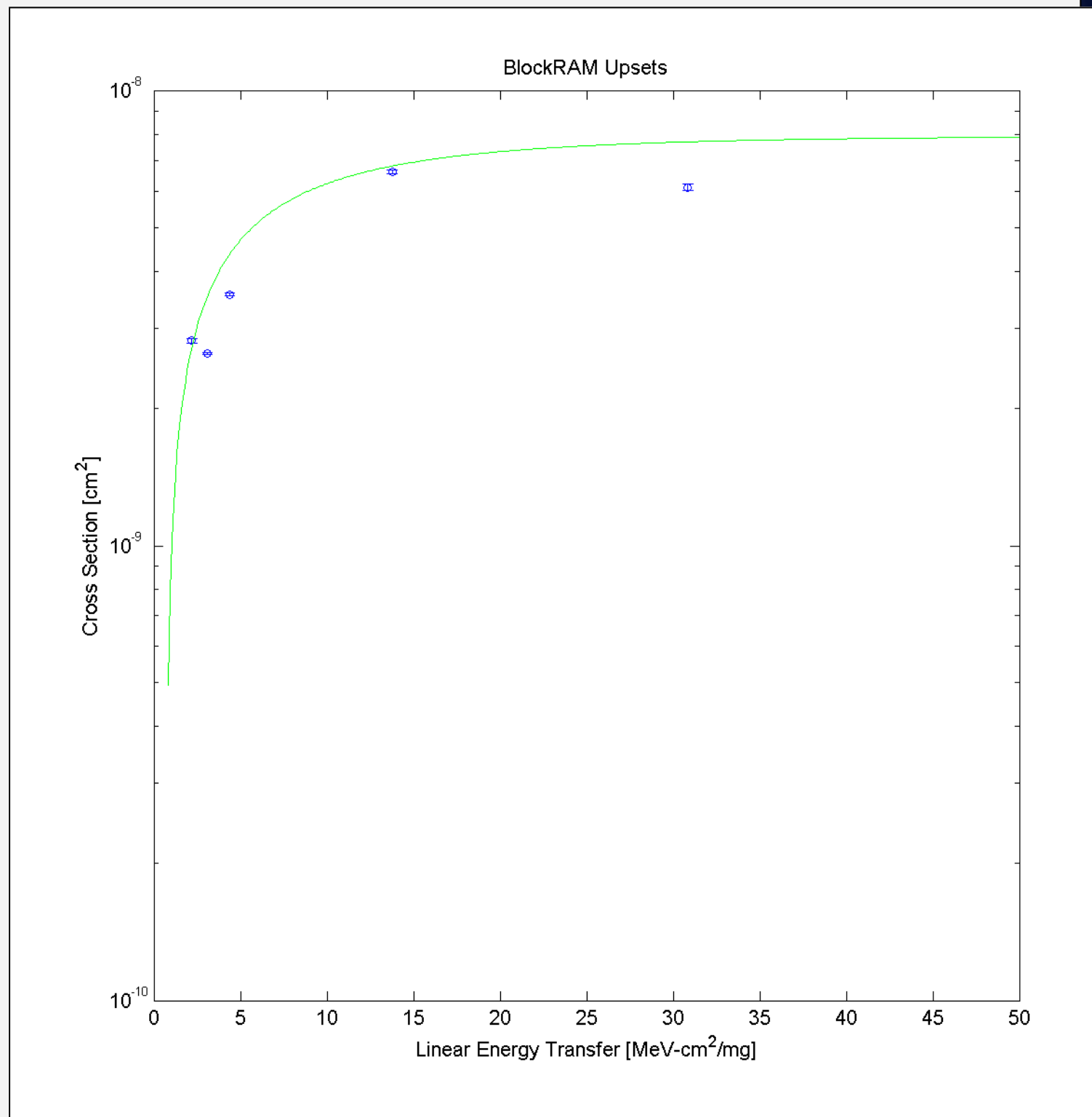
Weibull curve illustrating the per-bit cross-section for individual flip-flop upsets.



Weibull curve illustrating the reset event cross-section at the slice level.

III. BlockRAM™

- BlockRAM was tested by instantiating all of the available BlockRAM into test designs loaded into the Kintex-7, with some cells initialized to 1 and the others initialized to 0.
- BlockRAM was not exercised in the design or clocked during irradiation.
- Initial analysis indicates a bias in upsets weighted towards cells holding 1 values. Cells storing 1s were 5-6x more likely to upset than cells storing 0s. However, additional data is necessary for validation of this claim.



Weibull curve illustrating the overall average per-bit cross-section for individual BlockRAM bit upsets.

Beam Parameters

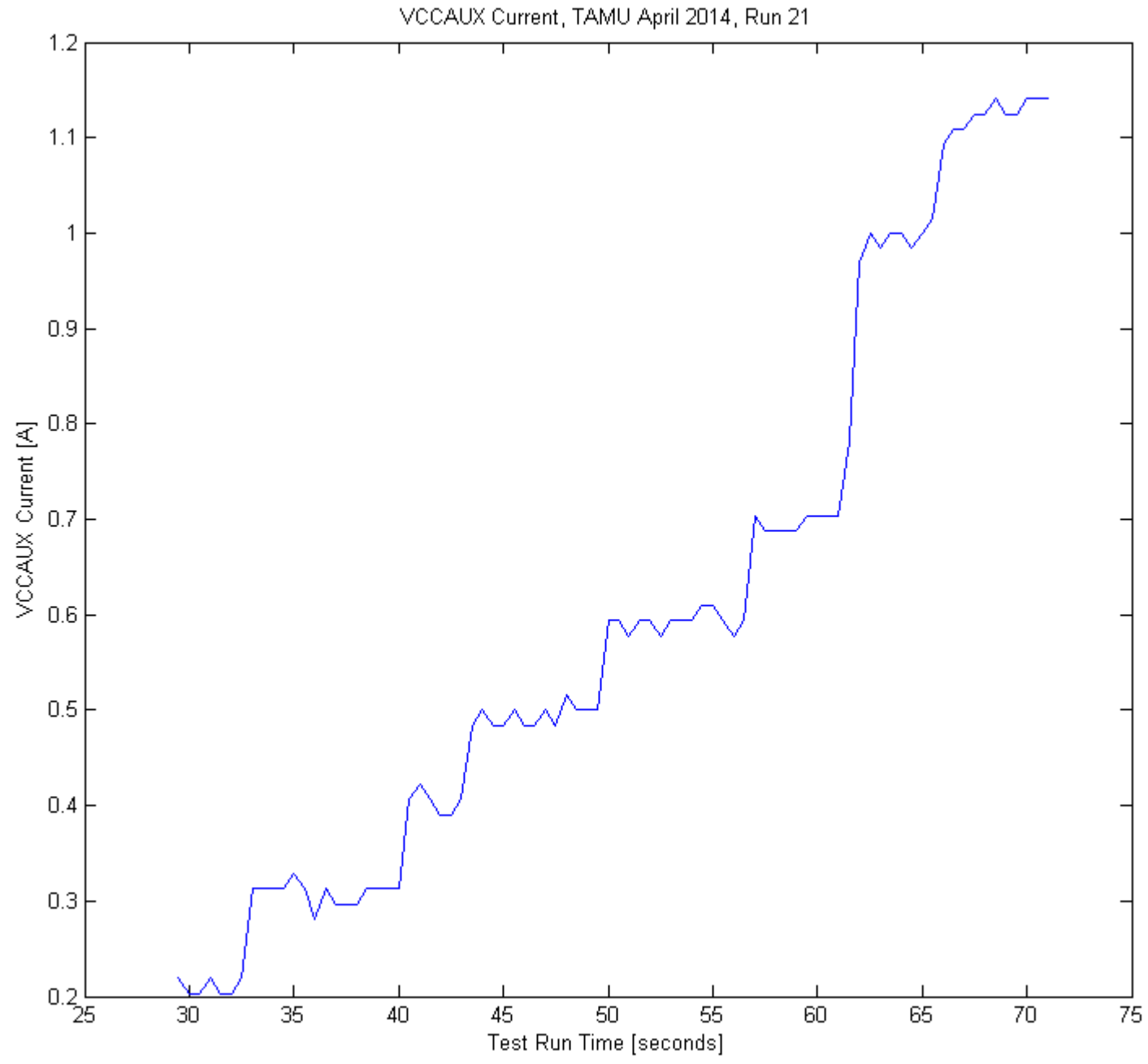
The device under test was irradiated with heavy ions at the Texas A&M University K500 Cyclotron and the Lawrence Berkeley National Laboratory 88-Inch Cyclotron. Testing utilized effective LETs from 1.5 to 126.1 MeV-cm²/mg.

Facility	TAMU	LBL	LBL	TAMU	LBL	TAMU	TAMU	TAMU	TAMU	LBL	LBL	TAMU	LBL	TAMU	LBL	TAMU	TAMU	TAMU
Effective LET	1.9	2.19	3.1	3.9*	4.38	6.3	6.9*	7.1*	8.8	9.7	13.8	24.2	30.9	32.9*	43.6	63.5	109.1	126.1
Initial LET	1.9	2.19	2.19	3.9	2.19	6.3	6.9	7.1	8.8	9.7	9.7	24.2	30.9	32.9	30.9	53.9	62.6	63.1
Angle	0	0	45	0	60	0	0	0	0	0	45	0	0	0	45	31.8	55	60

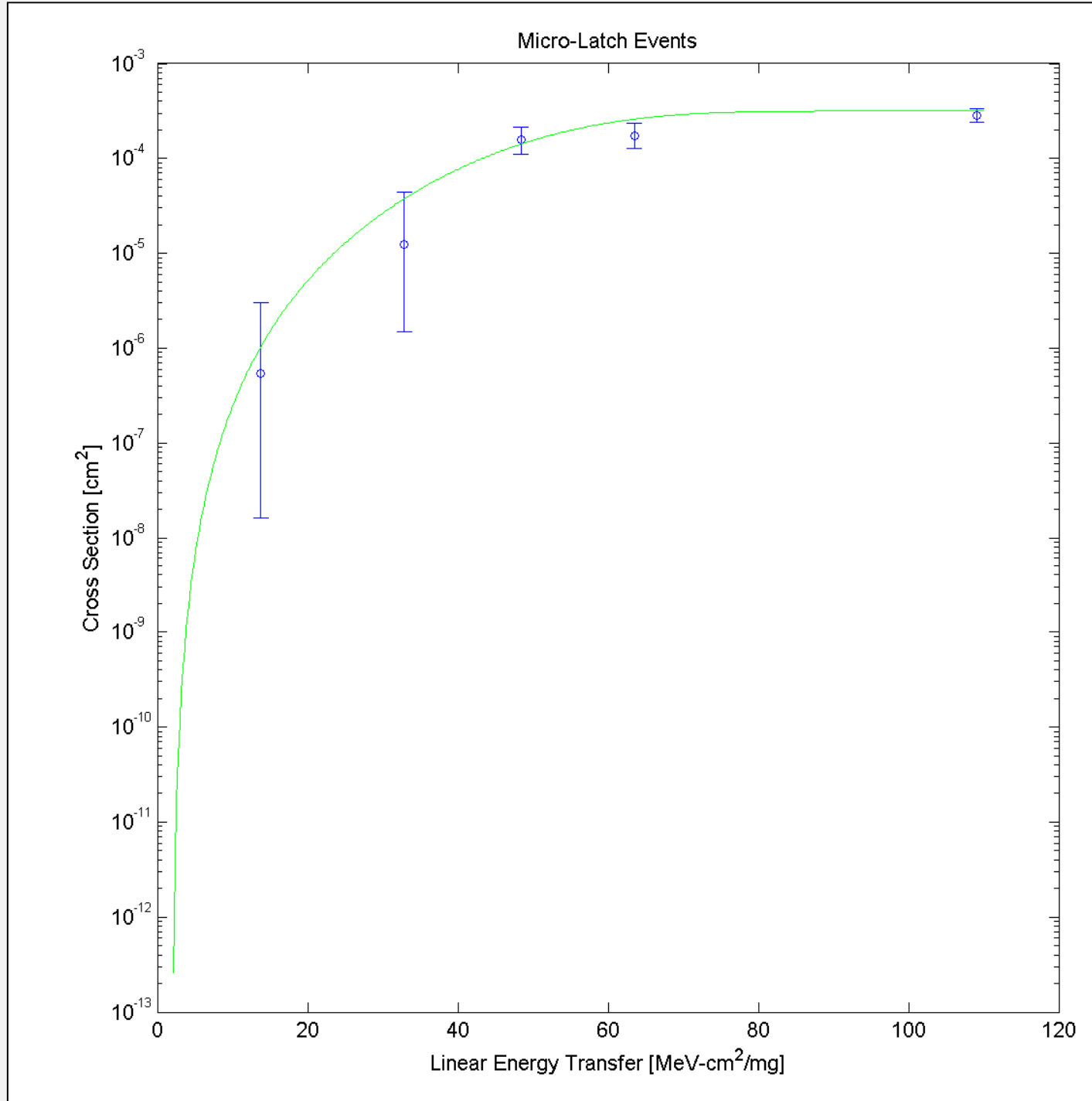
* = LET obtained through degrader

Device SEL Results

- Numerous current-step anomalies attributed to single event latchup were observed on the VCCAUX supply (1.8 V) when testing at high LET, high temperature, and maximum biases.
- Current would increase in steps of 125 mA ($\sigma_i=40$ mA).
- Current events would not clear through configuration scrubbing nor through assertion of the device's reset (PROG) pin.
- Current events cleared through power cycle or by reducing voltage to 1.2 V then returning to 1.8 V (demonstrating the holding voltage signature of parasitic bipolar latch structures [2] and indicates this is not from upset-induced contention or single-event functionality mode changes).
- No observable damage or loss of functionality, but have not yet fully exercised all circuits tied to VCCAUX.
- Event cross-section worsens at higher temperature and high biases.
- Lower LET threshold for this event appears to be around 15 MeV-mg/cm².
- All other Kintex-7 voltage rails appear to be latchup-free.



Current step events identified during SEL testing. Typical VCCAUX current draw is 210±16 mA. This run shows seven (possibly eight) current step events.



Weibull curve for the current step event.

Event Rates

The event rates from CREME96 are listed below, assuming a GEO orbit, solar minimum conditions, and 100 mils of aluminum shielding:

	Configuration Memory	User Flip-Flops	Flip-Flop Slice Resets	BlockRAM	Current-step SEL Events
Per Bit	1.52E-8 / day	1.33E-8 / day	3.2E-8 / slice / day	2.81E-7 / day	N/A
Per Device	1.12 / day	5.42E-3 / day	1.63E-3 / day	4.62 / day	9.2E-5 / day

References

- [1] Series FPGAs Overview (v1.14) [Online]. Available: http://www.xilinx.com/support/documentation/data_sheets/ds180_7Series_Overview.pdf, last accessed February 2, 2014.
- [2] Hu, G. J.; Bruce, R. H., "A CMOS Structure with high latchup holding voltage," *IEEE Electron Device Letters*, vol.5, no.6, pp.211-214, Jun 1984.
- [3] Wirthlin, M.; Lee, D.; Swift, G.; Quinn, H., "A Method and Case Study on Identifying Physically Adjacent Multi-Cell Upsets Using 28nm Interleaved and SECDED-Protected Arrays," submitted to *IEEE Transactions on Nuclear Science*, July 2014.